



SDI Review Form 1.6

Journal Name:	Journal of Engineering Research and Reports
Manuscript Number:	Ms_JERR_44923
Title of the Manuscript:	Improvement on Semiconductor Substrate Design with Package Modeling and Simulation for Mitigation of Delamination and Voids
Type of the Article	Original Research Article

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Compulsory REVISION comments		
Minor REVISION comments	Line 19 "integrate circuit" should read "Integrated Circuit" Line 22 "printed circuit board" should read "Printed Circuit Board" Line 25 What, which or where is "Device Z" Author should please clarify Line 48 Insert comma after "Currently" like this "Currently, DAF...." Line 65 Give full meaning of "cu". Not many readers will understand it means "Copper" Line 78 What is "um"? Give full meaning Line 115 What is "um"? Give full meaning Line 116 What is "um"? Give full meaning Line 146 Give full meaning of "CTE"	Line 19 – Done Line 22 – Done Line 25 – Done Line 48 – Done Line 65 – Done Line 78 – Done. Replaced with μm Line 115 – Done Line 116 – Done Line 146 – Done
Optional/General comments		

PART 2:

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	(If yes, Kindly please write down the ethical issues here in details)	